

L Number	Hits	Search Text	DB	Time stamp
1	3678	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS. ((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and (insitu in-situ)	USPAT; US-PGPUB	2003/11/03 14:14
2	279	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and (insitu in-situ)	USPAT; US-PGPUB	2003/11/03 14:14
3	2372	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and ((single one) with (process processing chamber))	USPAT; US-PGPUB	2003/11/03 14:15
5	50	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and ((single one) with (process processing chamber)) same ((heat\$5) same (cool\$5) same (etch\$5))	USPAT; US-PGPUB	2003/11/03 14:30
6	2	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and ((insitu in-situ) with (process processing chamber)) same ((heat\$5) same (cool\$5) same (etch\$5))	USPAT; US-PGPUB	2003/11/03 14:31
7	3604	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and ((insitu in-situ single one) with (process processing chamber)) p2 ((heat\$5) p2 (cool\$5) p2 (etch\$5))	USPAT; US-PGPUB	2003/11/03 14:39
11	49	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and ((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum)	USPAT; US-PGPUB	2003/11/03 14:53
12	2	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and ((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and ((heat\$5) same (cool\$5) same (etch\$5))	USPAT; US-PGPUB	2003/11/03 14:54
13	19	((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and ((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and (heat\$5) and (cool\$5) and (etch\$5)	USPAT; US-PGPUB	2003/11/03 16:05
14	0	((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and ((heat\$5) same (cool\$5) same (etch\$5))	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:05
15	0	((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and (heat\$5) and (cool\$5) and (etch\$5)	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:08
16	89	((insitu in-situ single one) with (process processing chamber)) and (heat\$5) and (cool\$5) and (etch\$5)	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:07
17	5	((insitu in-situ single one) with (process processing chamber)) and (heat\$5) and (cool\$5) and (etch\$5) and oxygen	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:07

19	0	((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and (heat\$5) and (cool\$5) and (etch\$5)	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:12
20	7	((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and (etch\$5)	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:09
21	2	((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and (heat\$5) and (cool\$5)	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:10
18	111	((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) and (heat\$5) and (cool\$5)	EPO; JPO; DERWENT; IBM_TDB	2003/11/03 16:11
22	100	((insitu in-situ single one) with (process processing chamber)) and ((descum descumming descumming descummed descumed scum) with (photoresist resist polyimide)) and (heat\$5) and (cool\$5) and (etch\$5)	USPAT; US-PGPUB	2003/11/03 16:19
23	6	((insitu in-situ single one) with (process processing chamber)) and ((descum descumming descumming descummed descumed scum) with (photoresist resist polyimide)) and ((heat\$5) same (cool\$5) same (etch\$5))	USPAT; US-PGPUB	2003/11/03 16:16
24	5	((insitu in-situ single one) with (process processing chamber)) and ((descum descumming descumming descummed descumed scum) with (oxygen)) and ((heat\$5) same (cool\$5) same (etch\$5))	USPAT; US-PGPUB	2003/11/03 16:16

25	79	((insitu in-situ single one) with (process processing chamber)) and ((descum descumming descumming descummed descumed scum) with (photoresist resist polyimide)) and (heat\$5) and (cool\$5) and (etch\$5) ) not (((((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and (((single one) with (process processing chamber)) same ((heat\$5) same (cool\$5) same (etch\$5)))) (((438/715) or (438/723) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and (((insitu in-situ with (process processing chamber)) same ((heat\$5) same (cool\$5) same (etch\$5)))) (((438/715) or (438/723) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and (((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed descumed scum) (((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and (((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed scum) and ((heat\$5) same (cool\$5) same (etch\$5))) (((438/715) or (438/723) or (438/725) or (438/907) or (438/963) or (216/67) or (134/1.2) or (134/1.3)).CCLS.) and (((insitu in-situ single one) with (process processing chamber)) and (descum descumming descumming descummed scum) and (heat\$5) and (cool\$5) and (etch\$5)) (((insitu in-situ single one) with (process processing chamber)) and ((descum descumming descumming descummed scum) with (photoresist resist polyimide)) and (heat\$5) same (cool\$5) same (etch\$5)) ) (((insitu in-situ single one) with (process processing chamber)) and ((descum descumming descumming descummed scum) with (oxygen)) and (heat\$5) same (cool\$5) same (etch\$5)) ))	USPAT; US-PGPUB	2003/11/03 16:20
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